ACT-SF41632 High Speed 128Kx32 SRAM / 512Kx32 Flash Multichip Module

AEROFLEX CIRCUIT TECHNOLOGY
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FEATURES

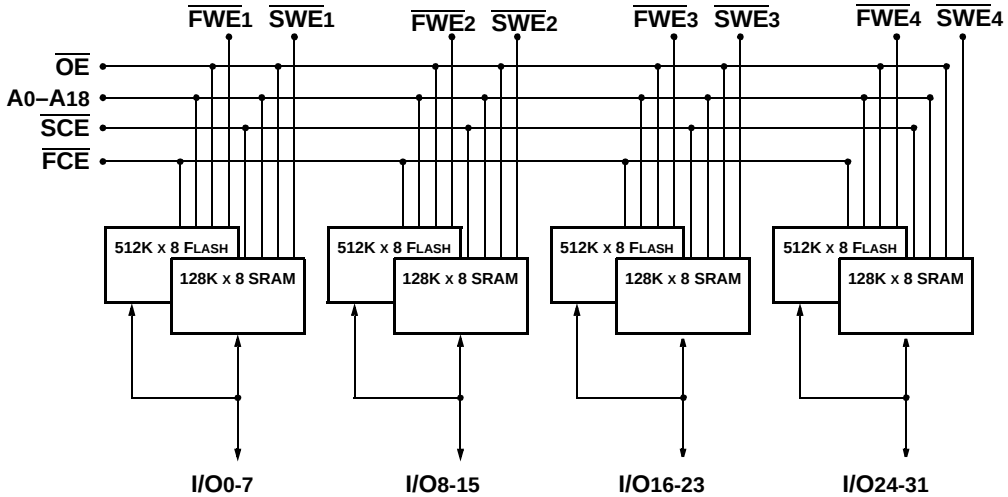
- 4 – 128K x 8 SRAMs & 4 – 512K x 8 Flash Die in One MCM
- Access Times of 25ns, 35ns (SRAM) and 60ns, 70ns, 90ns (Flash)
- Organized as 128K x 32 of SRAM and 512K x 32 of Flash Memory with Common Data Bus
- Low Power CMOS
- Input and Output TTL Compatible Design
- MIL-PRF-38534 Compliant MCMs Available
- Decoupling Capacitors and Multiple Grounds for Low Noise
- Commercial, Industrial and Military Temperature Ranges
- Industry Standard Pinouts
- TTL Compatible Inputs and Outputs
- Packaging – Hermetic Ceramic
  - 66–Lead, PGA-Type, 1.385"SQ x 0.245"max, Aeroflex code# "P1,P5 with/without shoulders)"
  - 68–Lead, Dual-Cavity CQFP(F2), 0.88"SQ x .20"max (.18 max thickness available, contact factory for details) *(Drops into the 68 Lead JEDEC .99"SQ CQFJ footprint)*

FLASH MEMORY FEATURES

- Sector Architecture (Each Die)
  - 8 Equal Sectors of 64K bytes each
  - Any combination of sectors can be erased with one command sequence.
- +5V Programing, +5V Supply
- Embedded Erase and Program Algorithms
- Hardware and Software Write Protection
- Page Program Operation and Internal Program Control Time.
- 10,000 Erase/Program Cycles

AEROFLEX LABS INC. ISO 9001 CERTIFIED

Block Diagram – PGA Type Package(P1 & P5) & CQFP(F2)



PIN DESCRIPTION

I/O0-31	Data I/O
A0–18	Address Inputs
$\overline{FWE}$1-4	Flash Write Enables
$\overline{SWE}$1-4	SRAM Write Enables
$\overline{FCE}$	Flash Chip Enable
$\overline{SCE}$	SRAM Chip Enable
$\overline{OE}$	Output Enable
NC	Not Connected
VCC	Power Supply
GND	Ground

Absolute Maximum Ratings

Symbol	Rating	Range	Units
T_C	Case Operating Temperature	-55 to +125	°C
T_{STG}	Storage Temperature	-65 to +150	°C
V_G	Maximum Signal Voltage to Ground	-0.5 to +7	V
T_L	Maximum Lead Temperature (10 seconds)	300	°C

Parameter	
Flash Data Retention	10 Years
Flash Endurance (Write/Erase Cycles)	10,000

Normal Operating Conditions

Symbol	Parameter	Minimum	Maximum	Units
V_{CC}	Power Supply Voltage	+4.5	+5.5	V
V_{IH}	Input High Voltage	+2.2	V_{CC} + 0.3	V
V_{IL}	Input Low Voltage	-0.5	+0.8	V

Capacitance

(V_{IN} = 0V, f = 1MHz, T_A = 25°C)

Symbol	Parameter	Maximum	Units
C_{AD}	A_0 – A_{18} Capacitance	80	pF
C_{OE}	$\overline{OE}$ Capacitance	80	pF
C_{WE1-4}	F/S Write Enable Capacitance	30	pF
C_{CE}	F/S Chip Enable Capacitance	50	pF
$C_{I/O}$	I/O_0 – I/O_{31} Capacitance	30	pF

This parameter is guaranteed by design but not tested

DC Characteristics

(V_{CC} = 5.0V, V_{SS} = 0V, Tc = -55°C to +125°C)

Parameter	Sym	Conditions	Min	Max	Units
Input Leakage Current	I_{LI}	V_{CC} = Max, V_{IN} = 0 to V_{CC}		10	µA
Output Leakage Current	I_{LO}	$\overline{FCE}$ = $\overline{SCE}$ = V_{IH}, $\overline{OE}$ = V_{IH}, V_{OUT} = 0 to V_{CC}		10	µA
SRAM Operating Supply Current x 32 Mode	I_{CC}x32	$\overline{SCE}$ = V_{IL}, $\overline{OE}$ = V_{IH}, f = 5MHz, V_{CC} = Max, $\overline{FCE}$ = V_{IH}		500	mA
Standby Current	I_{SB}	$\overline{FCE}$ = $\overline{SCE}$ = V_{IH}, $\overline{OE}$ = V_{IH}, f = 5MHz, V_{CC} = Max		80	mA
SRAM Output Low Voltage	V_{OL}	I_{OL} = 8 mA, V_{CC} = Min, $\overline{FCE}$ = V_{IH}		0.4	V
SRAM Output High Voltage	V_{OH}	I_{OH} = -4.0 mA, , V_{CC} = Min, $\overline{FCE}$ = V_{IH}	2.4		V
Flash Vcc Active Current for Read (1)	I_{CC1}	$\overline{FCE}$ = V_{IL}, $\overline{OE}$ = V_{IH}, $\overline{SCE}$ = V_{IH}		260	mA
Flash Vcc Active Current for Program or Erase (2)	I_{CC2}	$\overline{FCE}$ = V_{IL}, $\overline{OE}$ = V_{IH}, $\overline{SCE}$ = V_{IH}		300	mA
Flash Output Low Voltage	V_{OL}	I_{OL} = 12 mA, V_{CC} = Min, $\overline{SCE}$ = V_{IH}		0.45	V
Flash Output High Voltage	V_{OH1}	I_{OH} = -2.5 mA, , V_{CC} = Min, $\overline{SCE}$ = V_{IH}	0.85 x V_{CC}		V
Flash Low Vcc Lock Out Voltage	V_{LKO}		3.2	4.2	V

Notes: 1) The I_{CC} current listed includes both the DC operating current and the frequency dependent component (at 5MHz). The frequency component typically is less than 2mA/MHz, with $\overline{OE}$ at V_{IH} 2) I_{CC} active while Embedded Algorithim (program or erase) is in progress 3) DC test conditions: V_{IL} = 0.3V, V_{IH} = V_{CC} - 0.3V

SRAM AC Characteristics

(V_{CC} = 5.0V, V_{SS}= 0V, T_C = -55°C to +125°C)

Read Cycle

Parameter	Symbol	–025		–035		Units
		Min	Max	Min	Max	
Read Cycle Time	t_{RC}	25		35		ns
Address Access Time	t_{AA}		25		35	ns
Chip Select Access Time	t_{ACE}		25		35	ns
Output Hold from Address Change	t_{OH}	0		0		ns
Output Enable to Output Valid	t_{OE}		15		20	ns
Chip Select to Output in Low Z *	t_{CLZ}	3		3		ns
Output Enable to Output in Low Z *	t_{OLZ}	0		0		ns
Chip Deselect to Output in High Z *	t_{CHZ}		12		20	ns
Output Disable to Output in High Z *	t_{OHZ}		12		20	ns

* Parameters guaranteed by design but not tested

Write Cycle

Parameter	Symbol	–025		–035		Units
		Min	Max	Min	Max	
Write Cycle Time	t_{WC}	25		35		ns
Chip Select to End of Write	t_{CW}	20		25		ns
Address Valid to End of Write	t_{AW}	20		25		ns
Data Valid to End of Write	t_{DW}	15		20		ns
Write Pulse Width	t_{WP}	20		25		ns
Address Setup Time	t_{AS}	0		0		ns
Output Active from End of Write *	t_{OW}	0		0		ns
Write to Output in High Z *	t_{WHZ}		10		20	ns
Data Hold from Write Time	t_{DH}	0		0		ns
Address Hold Time	t_{AH}	0		0		ns

* Parameters guaranteed by design but not tested

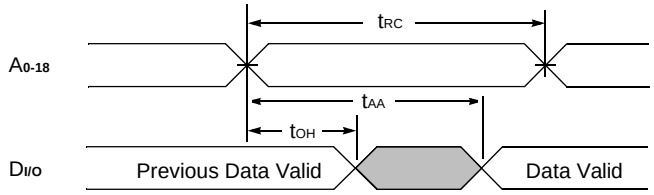
SRAM Truth Table

Mode	$\overline{SCE}$	$\overline{OE}$	$\overline{SWE}$	Data I/O	Power
Standby	H	X	X	High Z	Standby
Read	L	L	H	Data Out	Active
Output Disable	L	H	H	High Z	Active
Write	L	X	L	Data In	Active

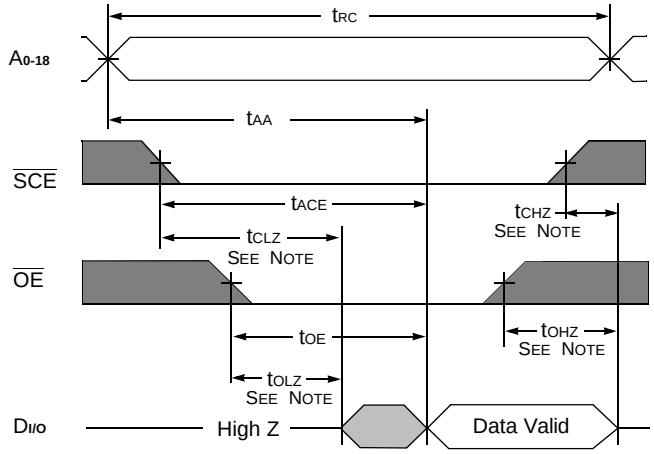
Timing Diagrams — SRAM

Read Cycle Timing Diagrams

Read Cycle 1 ($\overline{SCE}$ = $\overline{OE}$ = V_{IL}, $\overline{SWE}$ = V_{IH})

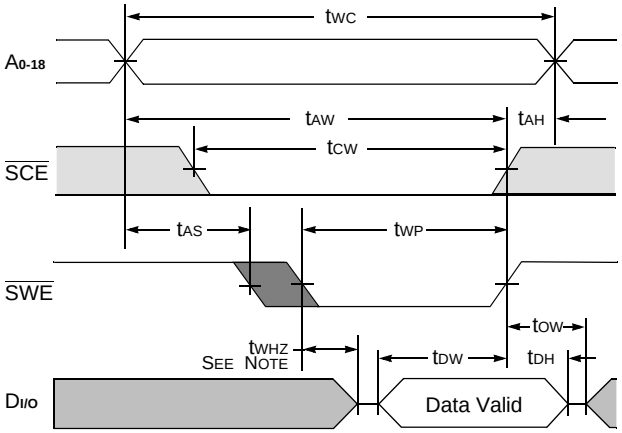


Read Cycle 2 ($\overline{SWE}$ = V_{IH})

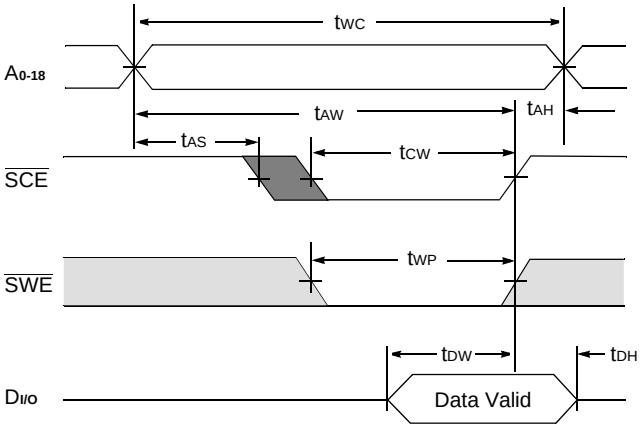


Write Cycle Timing Diagrams

Write Cycle ($\overline{SWE}$ Controlled, $\overline{OE}$ = V_{IH})

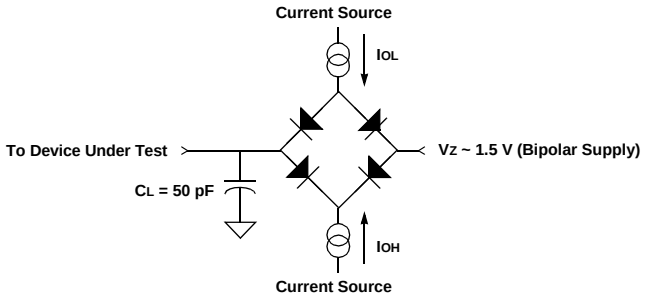


Write Cycle ($\overline{SCE}$ Controlled, $\overline{OE}$ = V_{IH})



Note: Guaranteed by design, but not tested.

AC Test Circuit



AC Test Conditions

Parameter	Typical	Units
Input Pulse Level	0 – 3.0	V
Input Rise and Fall	5	ns
Input and Output Timing Reference Level	1.5	V

Notes:
1) V_Z is programmable from -2V to +7V. 2) I_{OL} and I_{OH} programmable from 0 to 16 mA. 3) Tester Impedance Z_O = 75Ω. 4) V_Z is typically the midpoint of V_{OH} and V_{OL}. 5) I_{OL} and I_{OH} are adjusted to simulate a typical resistance load circuit. 6) ATE Tester includes jig capacitance.

Flash AC Characteristics – Read Only Operations

(Vcc = 5.0V, Vss = 0V, Tc = -55°C to +125°C)

Parameter	Symbol JEDEC	Symbol Stand'd	–60 Min	–60 Max	–70 Min	–70 Max	–90 Min	–90 Max	Units
Read Cycle Time	t_{AVAV}	t_{RC}	60		70		90		ns
Address Access Time	t_{AVQV}	t_{ACC}		60		70		90	ns
Chip Enable Access Time	t_{ELQV}	t_{CE}		60		70		90	ns
Output Enable to Output Valid	t_{GLQV}	t_{OE}		30		35		35	ns
Chip Enable to Output High Z (1)	t_{EHQZ}	t_{DF}		20		20		20	ns
Output Enable High to Output High Z(1)	t_{GHQZ}	t_{DF}		20		20		20	ns
Output Hold from Address, $\overline{CE}$ or $\overline{OE}$ Change, Whichever is First	t_{AXQX}	t_{OH}	0		0		0		ns

Note 1. Guaranteed by design, but not tested

Flash AC Characteristics – Write / Erase / Program Operations, $\overline{FWE}$ Controlled

(Vcc = 5.0V, Vss = 0V, Tc = -55°C to +125°C)

Parameter	Symbol JEDEC	Symbol Stand'd	–60 Min	–60 Max	–70 Min	–70 Max	–90 Min	–90 Max	Units
Write Cycle Time	t_{AVAC}	t_{WC}	60		70		90		ns
Chip Enable Setup Time	t_{ELWL}	t_{CE}	0		0		0		ns
Write Enable Pulse Width	t_{WLWH}	t_{WP}	40		45		45		ns
Address Setup Time	t_{AVWL}	t_{AS}	0		0		0		ns
Data Setup Time	t_{DVWH}	t_{DS}	40		45		45		ns
Data Hold Time	t_{WHDX}	t_{DH}	0		0		0		ns
Address Hold Time	t_{WLAX}	t_{AH}	45		45		45		ns
Write Enable Pulse Width High	t_{WHWL}	t_{WPH}	20		20		20		ns
Duration of Byte Programming Operation	t_{WHWH1}		14	TYP	14	TYP	14	TYP	µs
Sector Erase Time	t_{WHWH2}			30		30		30	Sec
Read Recovery Time before Write	t_{GHWL}		0		0		0		µs
Vcc Setup Time		t_{VCE}		50		50		50	µs
Chip Programming Time			50		50		50		Sec
Chip Enable Hold Time		t_{OEH} [1]	10		10		10		ns
Chip Erase Time	t_{WHWH3}			120		120		120	Sec

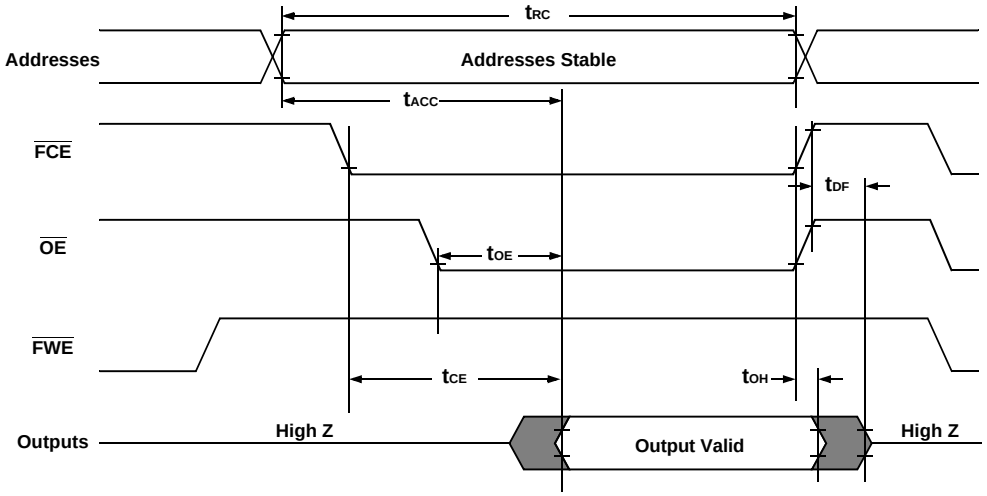
1. Toggle and Data Polling only.

Flash AC Characteristics – Write / Erase / Program Operations, $\overline{FCE}$ Controlled

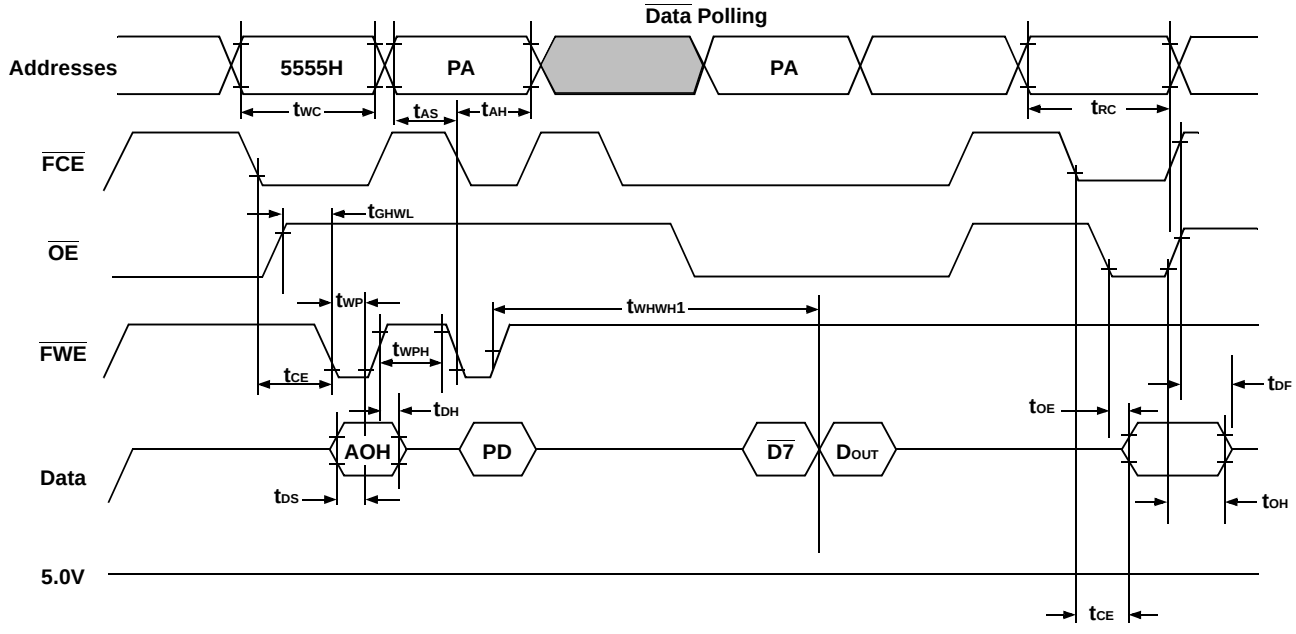
(Vcc = 5.0V, Vss = 0V, Tc = -55°C to +125°C)

Parameter	Symbol JEDEC	Symbol Stand'd	–60 Min	–60 Max	–70 Min	–70 Max	–90 Min	–90 Max	Units
Write Cycle Time	t_{AVAC}	t_{WC}	60		70		90		ns
Write Enable Setup Time	t_{WLEL}	t_{WS}	0		0		0		ns
Chip Enable Pulse Width	t_{ELEH}	t_{CP}	40		45		45		ns
Address Setup Time	t_{AVEL}	t_{AS}	0		0		0		ns
Data Setup Time	t_{DVEH}	t_{DS}	40		45		45		ns
Data Hold Time	t_{EHDX}	t_{DH}	0		0		0		ns
Address Hold Time	t_{ELAX}	t_{AH}	45		45		45		ns
Chip Enable Pulse Width High	t_{EHEL}	t_{CPH}	20		20		20		ns
Duration of Byte Programming	t_{WHWH1}		14	TYP	14	TYP	14	TYP	µs
Sector Erase Time	t_{WHWH2}			30		30		30	Sec
Read Recovery Time	t_{GHEL}		0		0		0		ns
Chip Programming Time				50		50		50	Sec
Chip Erase Time	t_{WHWH3}			120		120		120	Sec

AC Waveforms for Flash Memory Read Operations

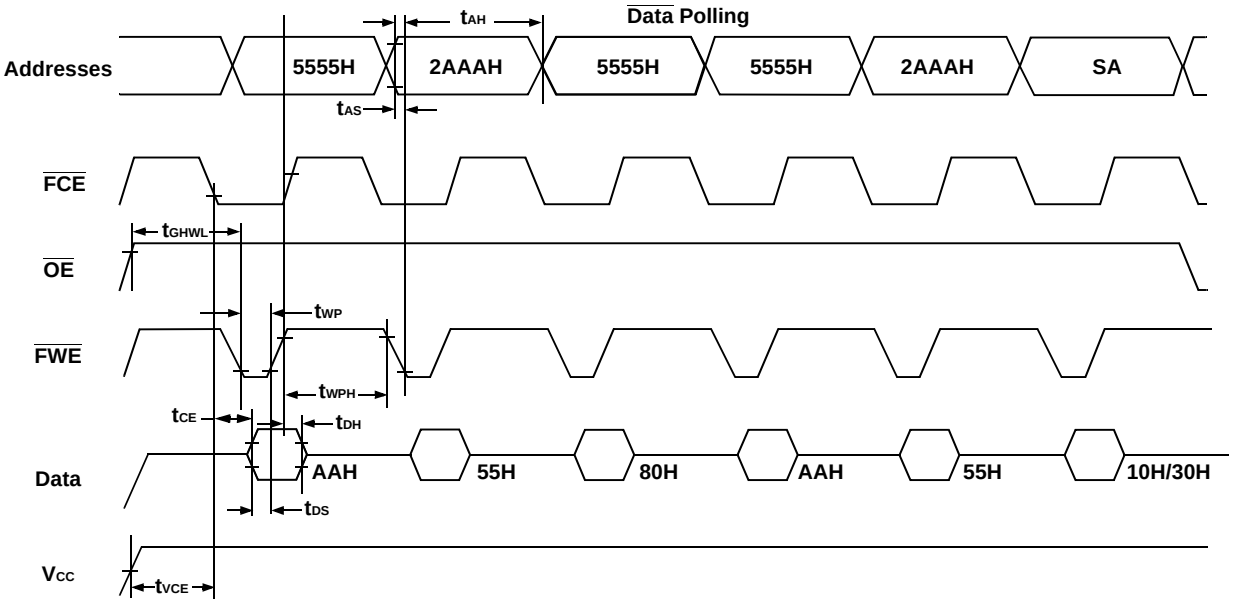


Write/Erase/Program Operation for Flash Memory, FWE Controlled



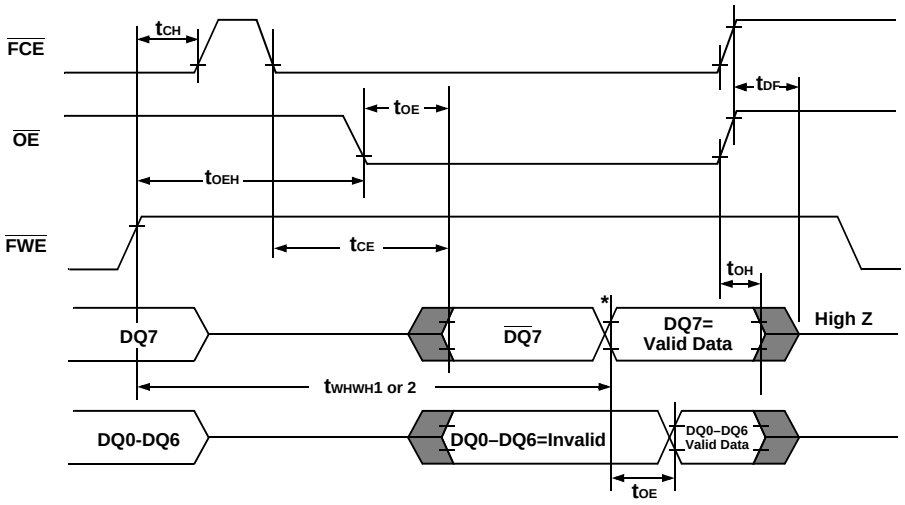
Notes:
1. PA is the address of the memory location to be programmed.
2. PD is the data to be programmed at byte address.
3. D7 is the 0utput of the complement of the data written to the deviced.
4. Dout is the output of the data written to the device.
5. Figure indicates last two bus cycles of four bus cycle sequence.

AC Waveforms Chip/Sector Erase Operations for Flash Memory



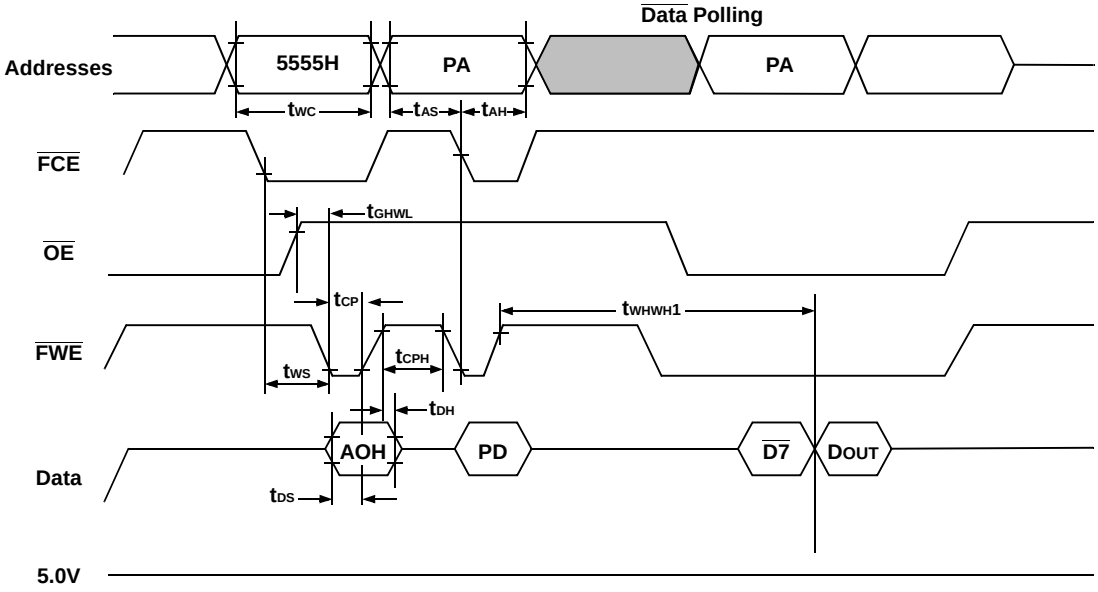
Notes:
1. SA is the sector address for sector erase.

AC Waveforms for Data Polling During Embedded Algorithm Operations for Flash Memory



** DQ7=Valid Data (The device has completed the Embedded operation).*

Write/Erase/Program Operation for Flash Memory, $\overline{FCE}$ Controlled



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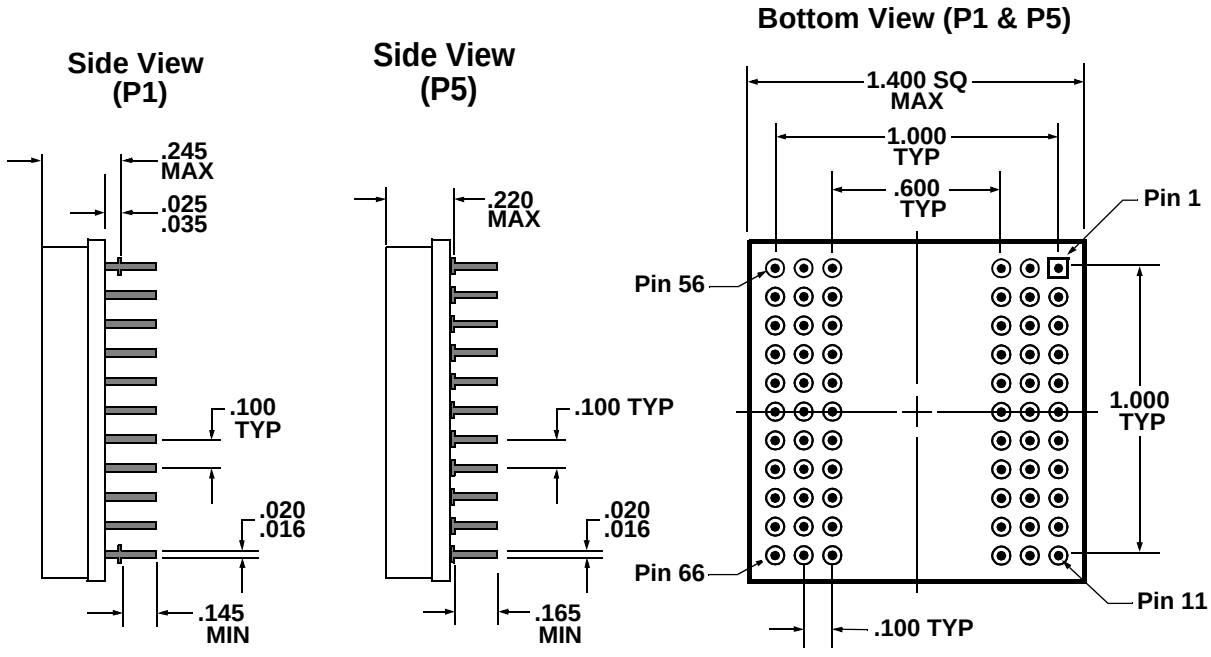
4. DOUT is the output of the data written to the device.
5. Figure indicates last two bus cycles of four bus cycle sequence.

Pin Numbers & Functions

66 Pins — PGA-Type							
Pin #	Function	Pin #	Function	Pin #	Function	Pin #	Function
1	I/O_8	18	A_{15}	35	I/O_{25}	52	$\overline{FWE_3}$
2	I/O_9	19	Vcc	36	I/O_{26}	53	$\overline{SWE_3}$
3	I/O_{10}	20	$\overline{FCE}$	37	A_7	54	GND
4	A_{14}	21	$\overline{SCE}$	38	A_{12}	55	I/O_{19}
5	A_{16}	22	I/O_3	39	$\overline{SWE_1}$	56	I/O_{31}
6	A_{11}	23	I/O_{15}	40	A_{13}	57	I/O_{30}
7	A_0	24	I/O_{14}	41	A_8	58	I/O_{29}
8	A_{18}	25	I/O_{13}	42	I/O_{16}	59	I/O_{28}
9	I/O_0	26	I/O_{12}	43	I/O_{17}	60	A_1
10	I/O_1	27	$\overline{OE}$	44	I/O_{18}	61	A_2
11	I/O_2	28	A_{17}	45	V_{CC}	62	A_3
12	$\overline{FWE_2}$	29	$\overline{FWE_1}$	46	$\overline{SWE_4}$	63	I/O_{23}
13	$\overline{SWE_2}$	30	I/O_7	47	$\overline{FWE_4}$	64	I/O_{22}
14	GND	31	I/O_6	48	I/O_{27}	65	I/O_{21}
15	I/O_{11}	32	I/O_5	49	A_4	66	I/O_{20}
16	A_{10}	33	I/O_4	50	A_5		
17	A_9	34	I/O_{24}	51	A_6		

"P1" — 1.385" SQ PGA Type Package Standard (with shoulders on Pins 1, 11, 56 & 66)
"P5" — 1.385" SQ PGA Type Special Order Package (without shoulders)



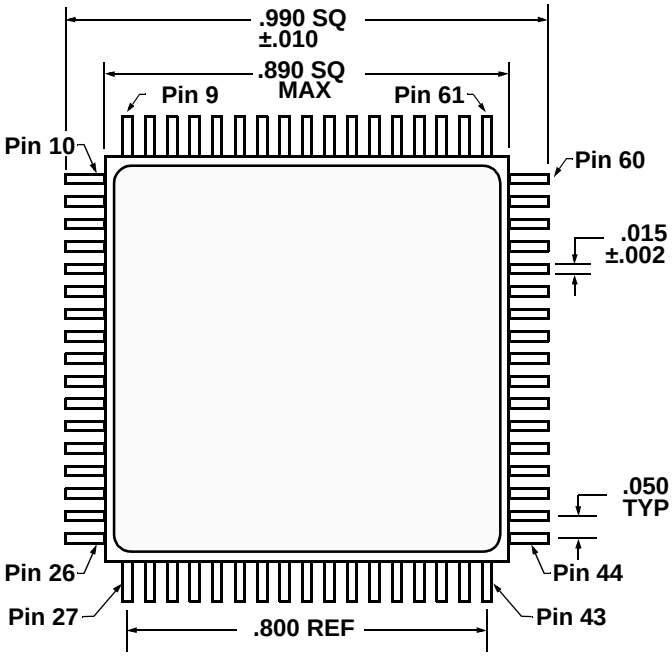
All dimensions in inches

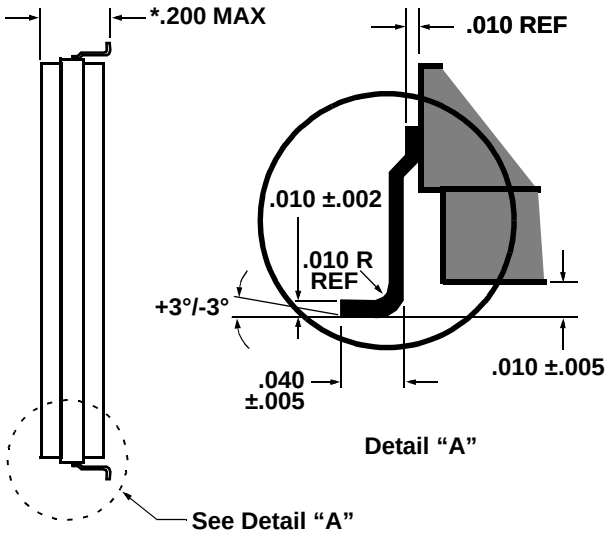
Pin Numbers & Functions

68 Pins — Dual-Cavity CQFP							
Pin #	Function	Pin #	Function	Pin #	Function	Pin #	Function
1	GND	18	GND	35	$\overline{OE}$	52	GND
2	$\overline{SWE_3}$	19	I/O_8	36	$\overline{SWE_2}$	53	FI/O_{23}
3	A_5	20	I/O_9	37	A_{17}	54	FI/O_{22}
4	A_4	21	I/O_{10}	38	$\overline{FWE_2}$	55	FI/O_{21}
5	A_3	22	I/O_{11}	39	$\overline{FWE_3}$	56	FI/O_{20}
6	A_2	23	I/O_{12}	40	$\overline{FWE_4}$	57	FI/O_{19}
7	A_1	24	I/O_{13}	41	A_{18}	58	FI/O_{18}
8	A_0	25	I/O_{14}	42	$\overline{SCE}$	59	FI/O_{17}
9	NC	26	I/O_{15}	43	$\overline{SWE_1}$	60	FI/O_{16}
10	I/O_0	27	V_{CC}	44	FI/O_{31}	61	V_{CC}
11	I/O_1	28	A_{11}	45	FI/O_{30}	62	A_{10}
12	I/O_2	29	A_{12}	46	FI/O_{29}	63	A_9
13	I/O_3	30	A_{13}	47	FI/O_{28}	64	A_8
14	I/O_4	31	A_{14}	48	FI/O_{27}	65	A_7
15	I/O_5	32	A_{15}	49	FI/O_{26}	66	A_6
16	I/O_6	33	A_{16}	50	FI/O_{25}	67	$\overline{FWE1}$
17	I/O_7	34	$\overline{FCE}$	51	FI/O_{24}	68	$\overline{SWE_4}$

Package Outline — Dual-Cavity CQFP "F2"

Top View





***.180 MAX available, call factory for details**

All dimensions in inches

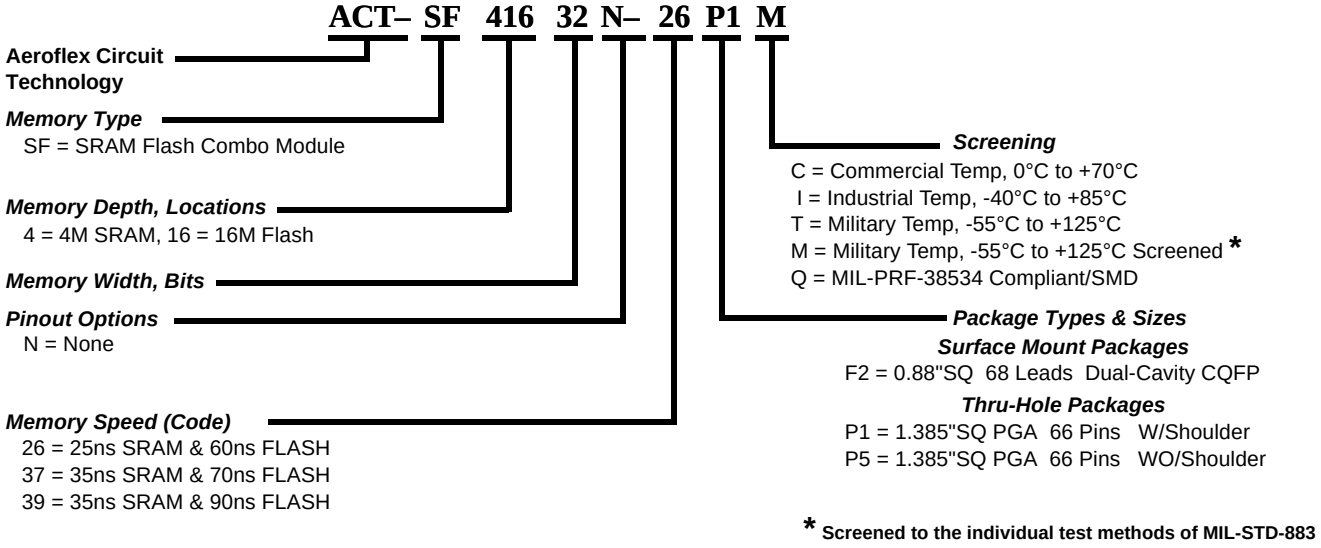
AEROFLEX
CIRCUIT TECHNOLOGY

Ordering Information

Model Number	DESC Part Number	Speed	Package
ACT-SF41632N–26P1X	TBD	25(S) / 60(F) ns	1.385"sq PGA-Type
ACT-SF41632N–37P1X	TBD	35(S) / 70(F) ns	1.385"sq PGA-Type
ACT-SF41632N–39P1X	TBD	35(S) / 90(F) ns	1.385"sq PGA-Type
ACT-SF41632N–26F2X	TBD	25(S) / 60(F) ns	.88"sq CQFP
ACT-SF41632N–37F2X	TBD	35(S) / 70(F) ns	.88"sq CQFP
ACT-SF41632N–39F2X	TBD	35(S) / 90(F) ns	.88"sq CQFP

Note: (S) = Speed for SRAM, (F) = Speed for FLASH

Part Number Breakdown



* **Screened to the individual test methods of MIL-STD-883**

Specifications subject to change without notice.

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